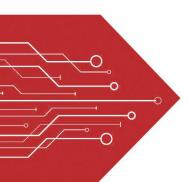
# MSKSEMI















**ESD** 

TVS

TSS

MOV

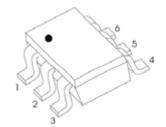
GDT

**PLED** 

# Broduct data sheet



**SOT-363** 

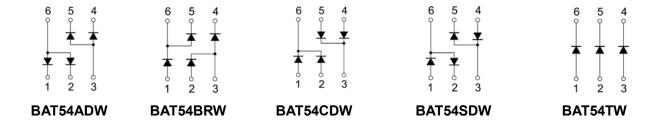


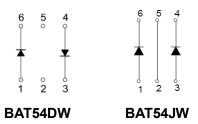
# BAT54ADW /BAT54BRW / BAT54CDW /BAT54SDW /BAT54TW BAT54DW/BAT54JW

SCHOTTKY BARRIER DIODE ARRAYS

#### **FEATURES**

- Low Forward Voltage Drop
- Fast Switching
- Small Surface Mount Package
- PN Junction Guard Ring for Transient and ESD Protection
- Available in Lead Free Version





#### MAXIMUM RATINGS ( T<sub>a</sub>=25℃ unless otherwise noted )

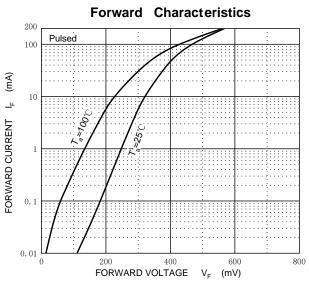
Symbol	Parameter	Value	Unit	
$V_{RRM}$	Repetitive Peak Reverse Voltage			
V <sub>RWM</sub>	Peak Working Reverse Voltage	30	V	
V <sub>R</sub>	DC Blocking Voltage			
Io	Forward Continuous Current	200	mA	
I <sub>FRM</sub>	Repetitive Peak Forward Current	300	mA	
I <sub>FSM</sub>	Non-repetitive Peak Forward Surge Current @t=8.3ms	600		
P <sub>D</sub>	Power Dissipation 200 mW		mW	
R <sub>OJA</sub>	Thermal Resistance From Junction To Ambient	500	°C/W	
T <sub>j</sub>	Operating Junction Temperature Range	-40 ~ +125	°C	
T <sub>stg</sub>	Storage Temperature Range	-55 ~ +150	℃	

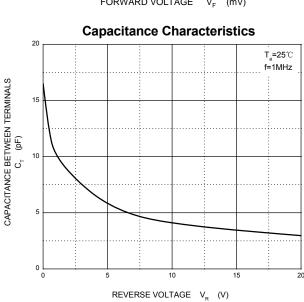


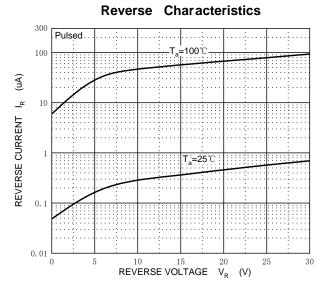


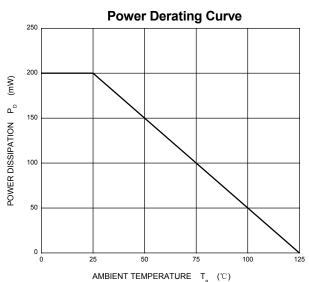
## ELECTRICAL CHARACTERISTICS ( $T_a$ =25 $^{\circ}$ C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Reverse voltage	$V_{(BR)}$	I <sub>R</sub> =100μA	30			V
Reverse current	I <sub>R</sub>	V <sub>R</sub> =25V			2	μA
	VF	I <sub>F</sub> =1mA			320	mV
Forward voltage		I <sub>F</sub> =10mA			400	
Forward voltage		I <sub>F</sub> =30mA			500	
		I <sub>F</sub> =100mA			1000	
Total capacitance	C <sub>tot</sub>	V <sub>R</sub> =1V,f=1MHz			10	pF
Reverse recovery time	t <sub>rr</sub>	$I_F = I_R = 10 \text{mA}, I_{rr} = 0.1 \times I_R, R_L = 100 \Omega$			5	ns



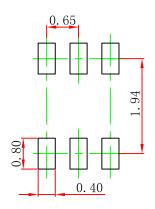






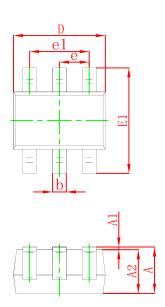


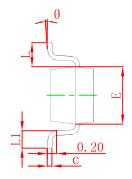
SOT-363



#### Note:

- 1.Controlling dimension:in millimeters. 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.





Symbol	Dimensions In Millimeters		Dimensions In Inches		
Syllibol	Min	Max	Min	Max	
Α	0.900	1.100	0.035	0.043	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.000	0.035	0.039	
b	0.150	0.350	0.006	0.014	
С	0.100	0.150	0.004	0.006	
D	2.000	2.200	0.079	0.087	
E	1.150	1.350	0.045	0.053	
E1	2.150	2.400	0.085	0.094	
е	0.650 TYP		0.026 TYP		
e1	1.200	1.400	0.047	0.055	
L	0.525 REF		0.021 REF		
L1	0.260	0.460	0.010	0.018	
θ	0°	8°	0°	8°	

### **REEL SPECIFICATION**

P/N	PKG	QTY
BAT54XXW	SOT-363	3000



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